#### 07/11/2018 504999729

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Ching-Chih Chang	07/06/2018
Yuan-Fu Ko	07/06/2018
Chih-Sheng Chang	07/06/2018

#### **RECEIVING PARTY DATA**

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

# **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	16033179	

#### CORRESPONDENCE DATA

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	NAUP3301USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	07/11/2018

#### **Total Attachments: 6**

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PATENT REEL: 046325 FRAME: 0517

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

# Title of Invention: METHOD FOR FORMING SEMICONDUCTOR DEVICE

No.3, Li-Hsin Road 2, Science	e-Based Industrial Park Hsin-	Chu City 300 Taiwan B O C
In consideration of the payment by	UNITED MICROELECTRONIC CORP.	having a postal address of
l hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made in this declar risonment of not more than five (5) ye	ation is punishable ears, or both.
I believe that I am the original inventapplication.	tor or an original joint inventor of a cla	aimed invention in the
The above-identified application was	s made or authorized to be made by	me.
☐ PCT international applicatio	n number	_filed on
☐ United States application nu	ımberfil	ed on, or
☑ The attached application, or		
As the below named inventor, I here This declaration is directed to:	eby declare that:	

# cience-Based industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF. I have hereunto set hand and seal this on the date(s) indicated.

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

> Page I of

NPO#NAU-P3301-USA:0 CUST#UMCD-2018-0056

LEGAL NAME OF INVENTOR(ASSIGNOR)

inventor:

**Ching-Chih Chang** 

Date:

JUL 0 6 2018

Signature:

Ching-Chih Chang

Page 2 of 6

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

### **Title of Invention:**

## METHOD FOR FORMING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application number		filed on,	or
□ PCT international application	number	filed on	
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invent application.	or or an original joint inventor of	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this de isonment of not more than five (5	claration is punishable b) years, or both.	
In consideration of the payment by	UNITED MICROELECTRO CORP.	NICS having a postal addr	ess of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	in-Chu City 300, Taiwan,	R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1. nd valuable consideration.	00), the receipt of which is here	eby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements wation and, in and to, all Letters Par r any continuations, continuation	vhich are disclosed in the tent to be obtained for said in-part, divisions, renewals,	ΞE
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbra h this assignment;	nce has been or will be made o	or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal			
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	plication, said invention and said ecessary or desirable to carry out	Letters Patent and said the proposes thereof.	
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.			

Page 3 of 6

NPO#NAU-P3301-USA:0 CUST#UMCD-2018-0056

# Docket No NAUP3301USA

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Yuan-Fu Ko	Date:	JUL 0 6 2018	
Signature:	Tuan Ja Ko			

Page 4 of 6

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

# Title of Invention:

# METHOD FOR FORMING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	n number	filed on	
The above-identified application was	made or authorized to be m	nade by me.	
I believe that I am the original invent application.	or or an original joint invento	r of a claimed invention	in the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	l false statement made in thi isonment of not more than fi	s declaration is punishave (5) years, or both.	able
In consideration of the payment by	UNITED MICROELECT CORP.	RONICS having a	postal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park	, Hsin-Chu City 300	, Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar of valuable consideration.	(\$ 1.00), the receipt of v	vhich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improveme tion and, in and to, all Letter rany continuations, continua	nts which are disclosed s Patent to be obtained ition-in-part, divisions, re	in the for said enewals,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encun n this assignment;	nbrance has been or wi	ll be made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent stify as to the same in any in	and legal equivalents a nterference, litigation pro	as may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention and secessary or desirable to carry	said Letters Patent and y out the proposes there	said eof.
Note: An application data sheet (PTC	D/SB/14 or equivalent), inclu	ding naming the entire	

Page 5 of 6

inventive entity, must accompany this form. Use this form for each additional inventor.

NPO#NAU-P3301-USA:0 CUST#UMCD-2018-0056

## Docket No NAUP3301USA

LEGAL NAME OF INVENTOR(ASSIGNOR) JUL 0 6 2018 Date: Inventor: **Chih-Sheng Chang** 

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F#NPO-P0002E-US1201 DSB0-107U014843

**RECORDED: 07/11/2018** 

NPO#NAU-P3301-USA:0

CUST#UMCD-2018-0056